



**THE DATASHEET OF
BS870-7-F**

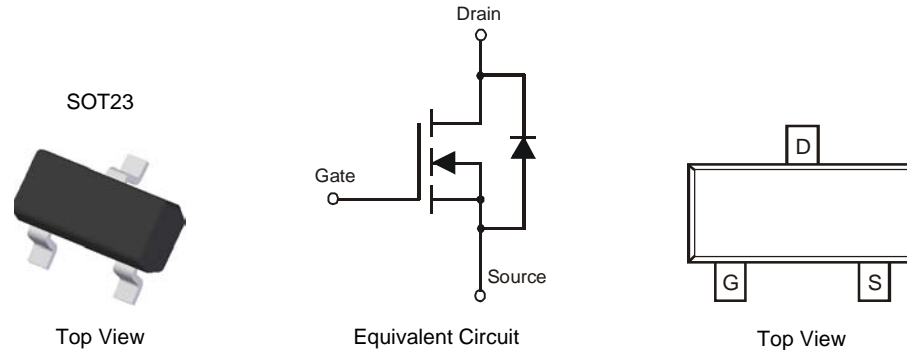


Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Notes 3 & 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)

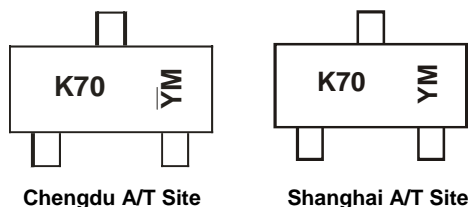


Ordering Information (Note 5)

| Part Number | Case | Packaging |
|-------------|-------|------------------|
| BS870-7-F | SOT23 | 3000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

Marking Information



K70 = Product Type Marking Code
 YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
 YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)
 Y or \bar{Y} = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

| Year | 1998 | 1999 | 2000 | 2001 | 2002 | 2003 | 2004 | ... | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 |
|-------|------|------|------|------|------|------|------|-----|------|------|------|------|------|------|------|
| Code | J | K | L | M | N | P | R | ... | Y | Z | A | B | C | D | E |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec | | | |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D | | | |

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|--|------------------|-------|-------|
| Drain-Source Voltage | V _{DSS} | 60 | V |
| Drain-Gate Voltage R _{GS} ≤ 1.0MΩ | V _{DGR} | 60 | V |
| Gate-Source Voltage | V _{GSS} | ±20 | V |
| Drain Current (Note 6) | I _D | 250 | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units |
|---|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 6) | P _D | 300 | mW |
| Thermal Resistance, Junction to Ambient | R _{θJA} | 417 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|-------------------------------------|---------------------|-----|-----|-----|------|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 60 | 80 | — | V | V _{GS} = 0V, I _D = 100μA |
| Zero Gate Voltage Drain Current | I _{DSS} | — | — | 0.5 | μA | V _{DS} = 25V, V _{GS} = 0V |
| Gate-Body Leakage | I _{GSS} | — | — | ±10 | nA | V _{GS} = ±15V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 7) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 1.0 | 2.0 | 3.0 | V | V _{DS} = V _{GS} , I _D = 250μA |
| Static Drain-Source On-Resistance | R _{DS(ON)} | — | 3.5 | 5.0 | Ω | V _{GS} = 10V, I _D = 0.2A |
| On-State Drain Current | I _{D(ON)} | 0.5 | 1.0 | — | A | V _{GS} = 10V, V _{DS} = 7.5V |
| Forward Transconductance | g _{FS} | 80 | — | — | mS | V _{DS} = 10V, I _D = 0.2A |
| DYNAMIC CHARACTERISTICS | | | | | | |
| Input Capacitance | C _{iss} | — | 22 | 50 | pF | V _{DS} = 10V, V _{GS} = 0V f = 1.0MHz |
| Output Capacitance | C _{oss} | — | 11 | 25 | pF | |
| Reverse Transfer Capacitance | C _{rss} | — | 2.0 | 5.0 | pF | |
| SWITCHING CHARACTERISTICS | | | | | | |
| Turn-On Delay Time | t _{D(ON)} | — | 2.0 | 20 | ns | V _{ES} = 10V, R _L = 150Ω, |
| Turn-Off Delay Time | t _{D(OFF)} | — | 5.0 | 20 | ns | V _{DS} = 10V, R _D = 100Ω |

- Notes:
6. Device mounted on FR-4 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 7. Short duration pulse test used to minimize self-heating effect.

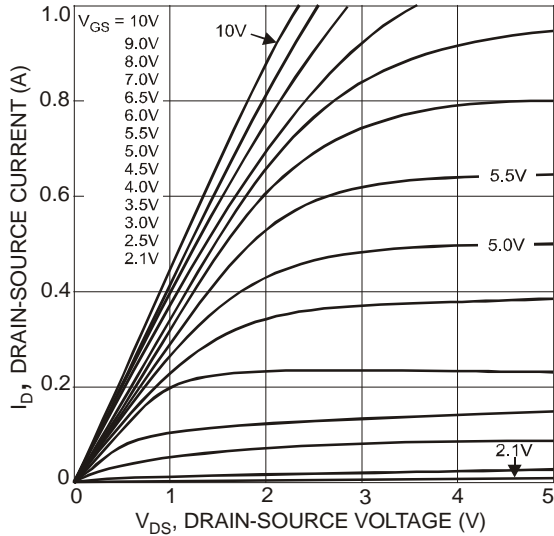


Fig. 1 On-Region Characteristics

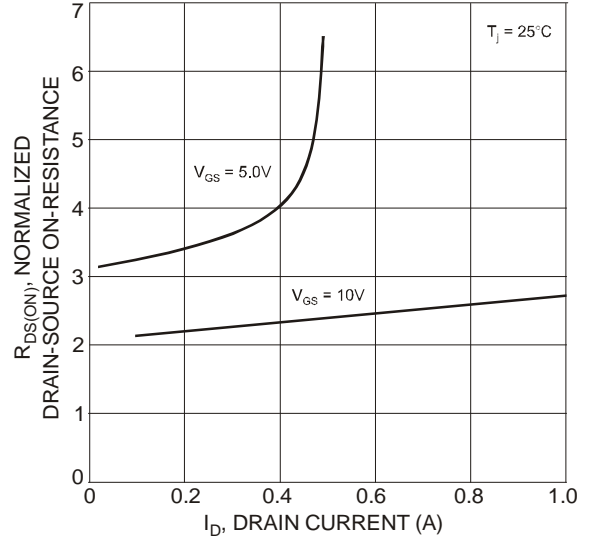


Fig. 2 On-Resistance vs. Drain Current

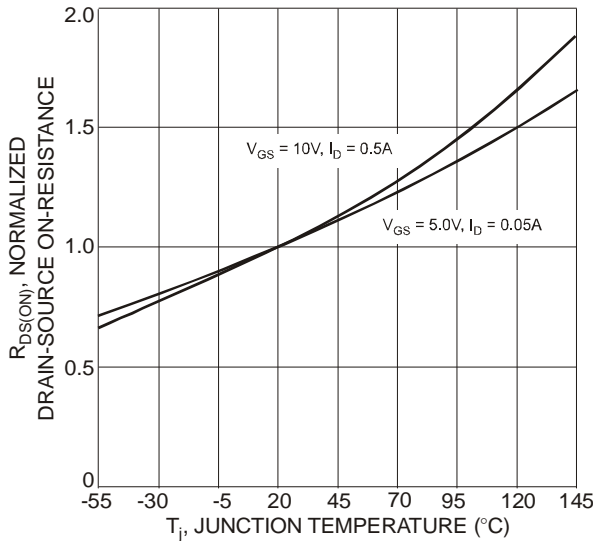


Fig. 3 On-Resistance vs. Junction Temperature

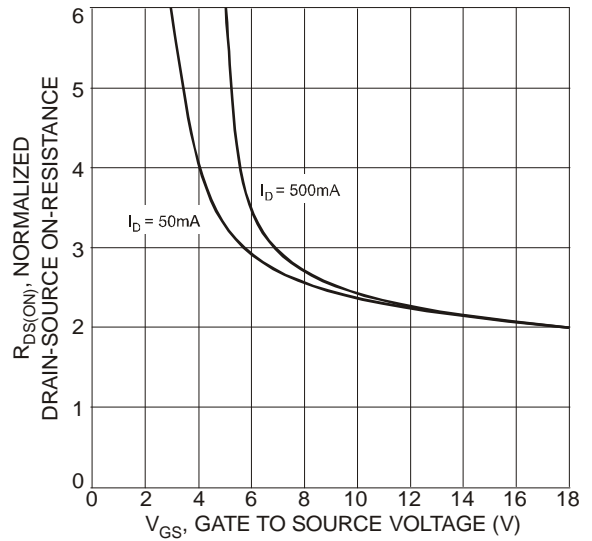


Fig. 4 On-Resistance vs. Gate-Source Voltage

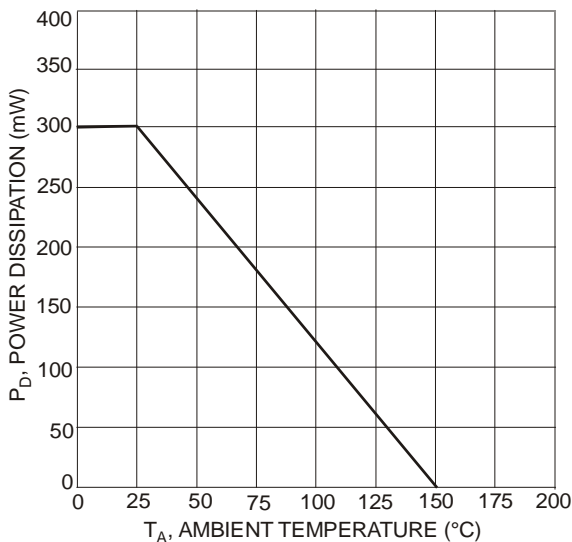
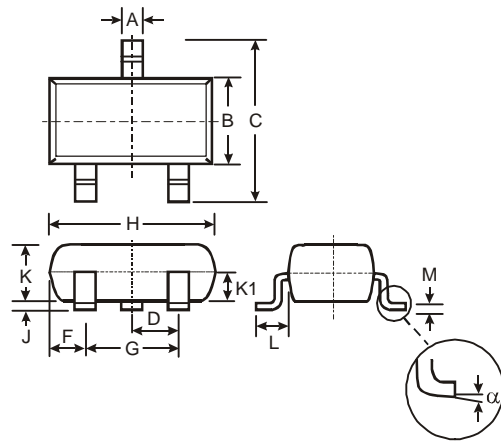


Fig. 5 Max Power Dissipation vs. Ambient Temperature

Package Outline Dimensions

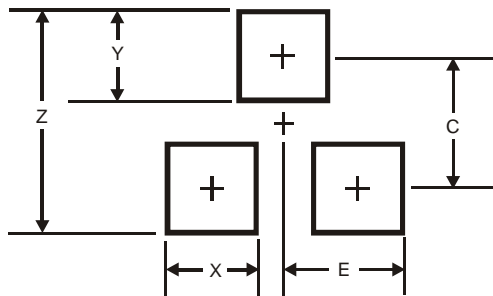
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



| SOT23 | | | |
|----------------------|-------|------|-------|
| Dim | Min | Max | Typ |
| A | 0.37 | 0.51 | 0.40 |
| B | 1.20 | 1.40 | 1.30 |
| C | 2.30 | 2.50 | 2.40 |
| D | 0.89 | 1.03 | 0.915 |
| F | 0.45 | 0.60 | 0.535 |
| G | 1.78 | 2.05 | 1.83 |
| H | 2.80 | 3.00 | 2.90 |
| J | 0.013 | 0.10 | 0.05 |
| K | 0.903 | 1.10 | 1.00 |
| K1 | - | - | 0.400 |
| L | 0.45 | 0.61 | 0.55 |
| M | 0.085 | 0.18 | 0.11 |
| α | 0° | 8° | - |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.9 |
| X | 0.8 |
| Y | 0.9 |
| C | 2.0 |
| E | 1.35 |

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